

Preface

Dear Distinguished Authors and Guests,

The Organizing Committee warmly welcomes you to 2013 the 2nd International Conference on Mechanical Engineering, Materials Science and Civil Engineering (ICMEMSCE2013) (TTP Conference ID: 919), held on 25-26 Oct., 2013 in Beijing, China.

The aim of the ICMEMSCE2013 is to present the latest research and results of scientists (professors, students, PhD Students, engineers, and post-doc scientist) related to Mechanical Engineering, Materials Science and Civil Engineering topics. This conference provides opportunities for the different areas delegates to exchange new ideas and application experiences face to face, to establish business or research relations and to find global partners for future collaboration.

After the peer-review process, the submitted papers were selected on the basis of originality, significance, and clarity for the purpose of the conference. The selected papers and additional late-breaking contributions to be presented as lectures will make an exciting technical program. The conference program is extremely rich, featuring high-impact presentation. We hope that the conference results constituted significant contribution to the knowledge in these up to date scientific field.

The proceeding records the fully refereed papers presented at the conference. The main conference themes and tracks are Mechanical Engineering, Materials Science and Civil Engineering: Mechanical Engineering, Material Engineering, Manufacturing and Design Science, Mechatronics, Information and Automation, Modeling, Simulation, Civil Engineering. Hopefully, all participants and other interested readers benefit scientifically from the proceedings and also find it stimulating in the process.

On behalf of the organizing committee, I would like to especially thank Saskia, Anne, Tanja, Dorte and all the editors from Trans Tech Publications for their great support to ICMEMSCE2013. Without their excellent editorial work, ICMEMSCE2013 will not be published so timely and successfully.

Finally we wish all the authors and attendees of ICMEMSCE2013 a unique, rewarding and enjoyable memory at ICMEMSCE2013 in Beijing, China. We look forward to your participation in the 3rd ICMEMSCE2014.

With our warmest regards,

Ikuo IHARA

The ICMEMSCE2013 Conference Guest editor

Oct. 31, 2013

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